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Box Patent Application
Assistant Commissioner of Patents
Washington, D.C. 20231

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Transmitted herewith for filing is the patent application of:

Applicants: Chong, David; Lee, HK; Allen, Howard; Martin, Stephen
Title: Packaging System for Die-Up Connection of a Die-Down Oriented
Integrated Circuit
Attorney Docket No. 17732-3856000

Pages of Specification: 6 Pages of Claims: 3 (w/ 14 total/2 indep)
Pages of Abstract: 1 Sheets of Drawings: 3
Information Disclosure Prior Art Citations: 6
Statement: 2 Assignee: Fairchild Semiconductor Corp.

Basic filing fee	710.00
Total claims in excess of 20 x 18.00	- 0 -
Independent claims in excess of 3 x \$80.00	- 0 -
Multiple dependent claims	- 0 -
Recordation fee (if applicable)	- 0 -
TOTAL FILING FEE	710.00

☒ A check in the amount of \$710.00 is enclosed.

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- ☒ Filing Fee
☒ Any additional fees associated with this paper or during the pendency of this application.

Respectfully submitted,

Date: March 30, 2001

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27723

PATENT TRADEMARK OFFICE

CERTIFICATE OF MAILING

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